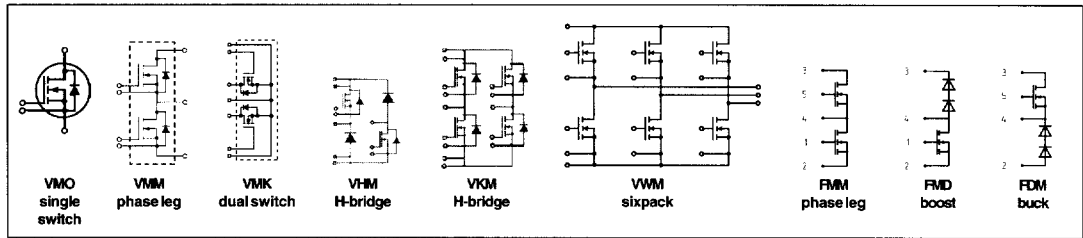









MOSFET Modules



N Channel Enhancement Types

suffix "F" = HiPerFET™ technology with intrinsic diode

Type	V _{DSS} V	I _{DS} A T _C = 25°C	I _{DS} A T _C = 80°C	R _{DS(on)} m T _C = 25°C	t _r ns	t _{ns} ns	R _{th(j-c)} K/W	ther- mistor	Fig. No.	Package style	
▶ New										Outline drawings on page 91-100	
▶ VMO 150-01P1	100	150	110	8	65	90	0.25		25	Fig. 26 TO-240AA Weight = 90 g  Fig. 28 Weight = 130 g  Fig. 33 Weight = 250 g  Fig. 25 ECO-PAC 2 Weight = 24 g See data sheet for pin arrangement  Fig. 80 Weight = 250 g  Fig. 82 Weight = 250 g  Fig. 74 Weight = 80 g 	
▶ VMO 550-01F	100	590	440	2.1	200	300	0.057		33		
▶ VMO 650-01F	100	690	520	1.8	200	300	0.048		33		
▶ VMO 580-02F	200	580	440	3.2	350	500	0.048		82		
▶ VMO 40-05P1	500	41	31	100	45	60	0.3		25		
▶ VMO 60-05F	500	60	44	65	30	250	0.21		26		
▶ VMO 80-05P1	500	82	62	50	45	60	0.16		25		
dual switch modules - common source configuration											
▶ VMK 165-007T	70	165	112	6	110	280	0.32		26		
▶ FMK 75-01F	100	75	50 / 90 °C	21	60	60	0.50		84		
▶ VMK 90-02T2	200	84	63	25	100	80	0.33		84		
MOSFET modules - phase leg configuration											
▶ FMM 150-0075P	75	150	120 / 90°C	4.7	60	60	0.60		84		
▶ FMM 75-01F	100	75	50 / 10°C	21	60	60	0.50		84		
▶ VMM 650-01F	100	680	500 / 90°C	1.8	200	250	0.08		80		
▶ FMM 65-015P	150	65	50 / 90°C	13	100	80	0.60		84		
▶ VMM 45-02F	200	45	34	39	25	200	0.63		26		
▶ VMM 85-02F	200	84	63	20	100	200	0.33		28		
▶ VMM 300-03F	300	290	220	7.4	150	300	0.08		33		
▶ VMM 90-09F	900	85	65	76	140	180	0.08		80		
MOSFET modules - H bridge configuration											
▶ VHM 25-05P1	500	24	18	230	30	33	0.5		25		
▶ VKM 60-01P1	100	63	47	25	60	60	0.45		25		
▶ VKM 40-06P1*	600	40	30	70	10	95	0.45		25		
sixpack modules with Trench Gate Power MOSFETs											
▶ VWM 350-0075P	75	350	250	2.3	60	75	0.26		74		
MOSFET modules - boost configuration											
▶ FMD 21-05QC	500	21	15 / 90°C	180	16	30	1.50		84		
MOSFET modules - buck configuration											
▶ FDM 100-0045SP	45	100	80 / 90°C	5.7	155	115	1.0		84		
▶ FDM 21-05QC	500	21	15 / 90°C	180	16	30	0.50		84		
<p>COOLMOS™ Power Semiconductor</p> <p>CoolMOS™ is a trademark of Infineon Technologies</p> <p>Fig. 84 ISOPLUS i4-PAC™ Weight = 9 g</p> 